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(54) CHIP SUCTION METHOD OF DIE BONDING DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To accelerate the working rate of a die bonding device by a method wherein, after abutting a chip against a tool, a push up pin in the state of holding a chip together with a tool is lifted up following after the tool.

SOLUTION: After moving a tool 1 on the home position to the position above an aligned chip 2, the tool 1 is lowered to be stopped on a stand-by position separating from the chip 2 by a specific length L. Next, a push up pin 3 is lifted to push up the chip 2 through the intermediary of a sheet 4 for releasing the chip 2 from the sheet 4 simultaneously abutting the chip 2 against the tool 1. Next, after detecting the bottom position by a grounding sensor, the push up pin 3 is lifted up by the previously set up push up amount and then both of the tool 1 and the push up pin 3 are lifted up to make the tool 1 suck up the chip 2. Accordingly, the working rate of a die bonding device can be increased.

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